MRSI-LEAP

ULTRA HIGH SPEED DIE BONDER

- Very high throughput
- Exceptionally stable, up to ±1μm @ 3σ placement accuracy
- Supports multiple wafers and multiple automated tool changes

MRSI Mycronic has been serving optoelectronic customers for the past 40+ years and understands their requirement to scale efficiently in today’s fast-paced marketplace.

Applications & Features

- Ultra-high placement accuracy achieved via intelligent motion control and high-resolution vision alignment
- Unmatched Throughput: Automated material handling and smart multi-tool switching system
- Supports multiple epoxy processes including stamping, dispensing, UV curing, and flip-chip assembly
- Proprietary Multi-die Eutectic Bonding: Solves double reflow issues in multi-die heating processes for reliable bonding
- Broad application compatibility: Suitable for AI optical modules, silicon photonics, LiDAR systems, and optical sensing applications

Configuration Highlights

- Advanced machine vision and tool design
- Modular design and field upgradeable
- Supports two 8-inch wafers and two 6-inch wafers
- Built-in conveyor and magazine design for high efficiency and throughput
- Automated dispensing and UV cure options available

Value to our Customers

- Industry-leading throughput, ultra-high accuracy, and long term stability in high-volume manufacturing, capable of achieving over 1,000 units per hour (UPH)
- Easy to use icon-based interface running on a Windows™ platform for ease of programming, and low-cost machine maintenance
- Industry-leading local technical support teams and application expertise
- 40+ years of experience in the industry with reliable 24/7 field operations

North America
554 Clark Rd., Tewksbury, MA
USA 01876
Tel: +1 978 667 9449
sales.mrsi@mycronic.com
mrsi.mycronic.com

MRSI China
101, Block A, Huahan
Innovation Park,
Langshan Road, Shenzhen,
China 518057
Tel: +86 755 26414155

MRSI EMEA
(Distributor and Demo Center)
Distek Strumenti & Misure Srl
Via Guglielmo Marconi, 15,
80125 Napoli NA, Italy
Tel: +39 348 3837817
marco@distek.it

June 2025